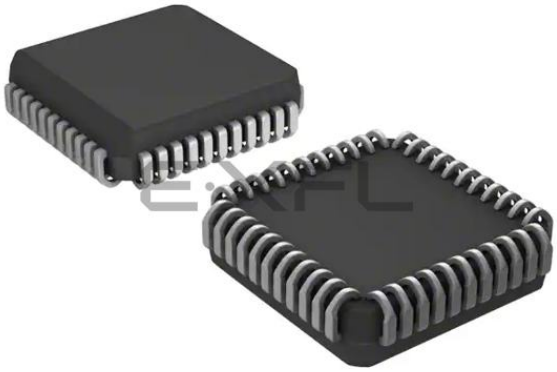

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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	Z8
Core Size	8-Bit
Speed	20MHz
Connectivity	EBI/EMI, UART/USART
Peripherals	-
Number of I/O	24
Program Memory Size	-
Program Memory Type	ROMless
EEPROM Size	-
RAM Size	236 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/zilog/z86c9320vsc00tr

GENERAL DESCRIPTION (Continued)

There are 256 registers located on-chip and organized as 236 general-purpose registers, 16 control and status registers, and four I/O port registers. The register file can be divided into sixteen groups of 16 working registers each. Configuration of the registers in this manner allows the use of short format instructions; in addition, any of the individual registers can be accessed directly. There are an additional 17 registers implemented in the Expanded Register File in Banks D and E. Two of the registers may be used as general-purpose registers, while 15 registers supply the data and control functions for the Multiply/Divide Unit and Counter/Timer blocks.

Notes:
All Signals with a preceding front slash, "/", are active Low, e.g.: B/W (WORD is active Low); /B/W (BYTE is active Low, only).

Power connections follow conventional descriptions below:

Connection	Circuit	Device
Power	V_{CC}	V_{DD}
Ground	GND	V_{SS}

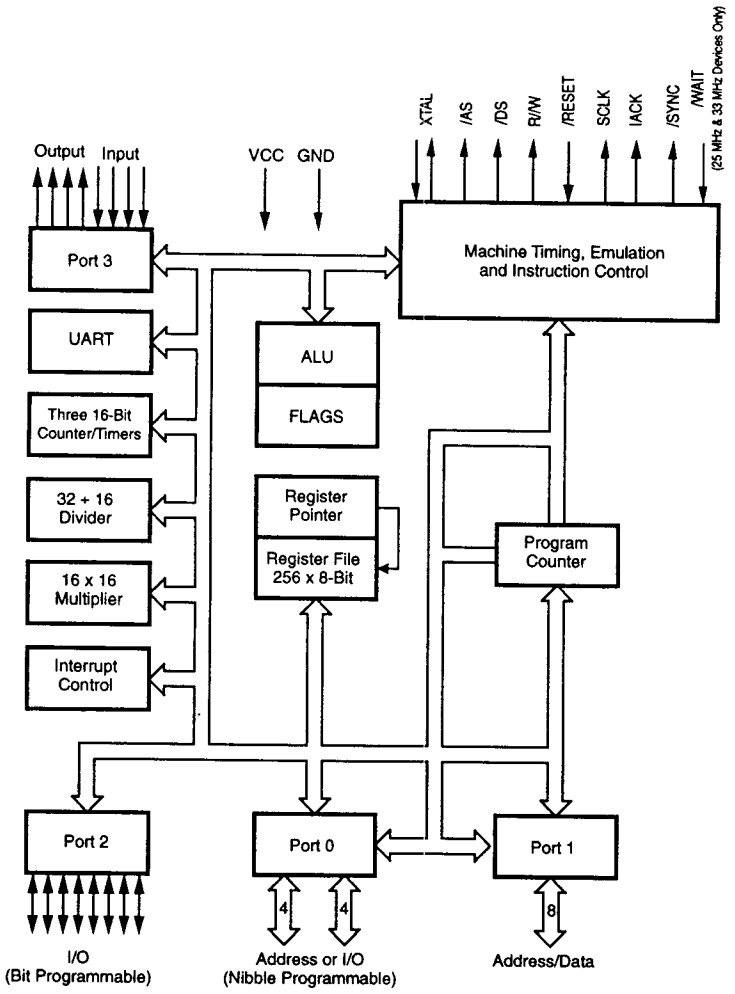


Figure 1. Functional Block Diagram

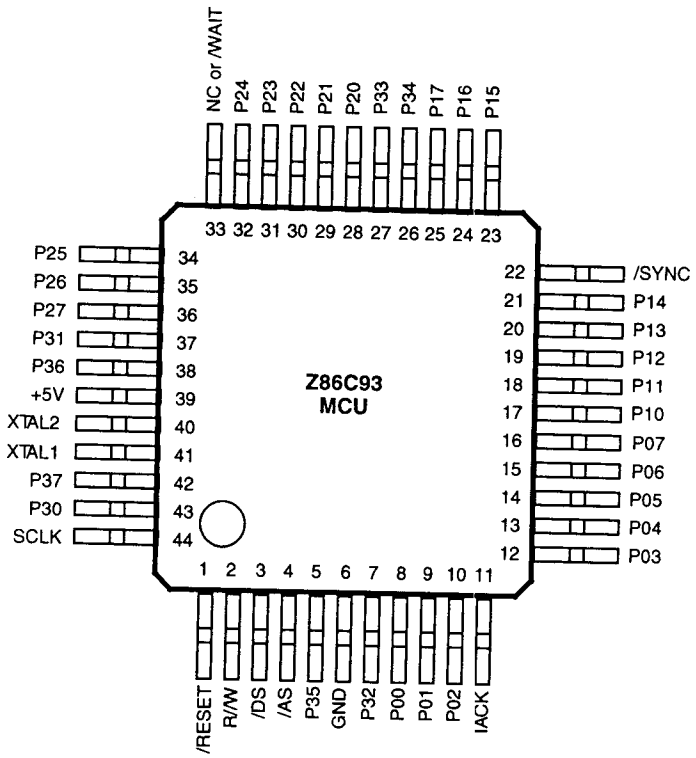


Figure 5. 44-Pin QFP

Table 3. 44-Pin QFP Pin Identification

No	Symbol	Function	Direction
1	/RESET	Reset	Input
2	R/W	Read/Write	Output
3	/DS	Data Strobe	Output
4	/AS	Address Strobe	Output
5	P35	Port 3 pin 5	Input
6	GND	Ground GND	Input
7	P32	Port 3 pin 2	Input
8-10	P00-P02	Port 0 pin 0,1,2	In/Output
11	IACK	Int. Acknowledge	Output
12-16	P03-P07	Port 0 pin 3,4,5,6,7	In/Output
17-21	P10-P14	Port 1 pin 0,1,2,3,4	In/Output
22	/SYNC	Synchronize Pin	Output
23-25	P15-P17	Port 1 pin 5,6,7	In/Output
26	P34	Port 3 pin 4	Output
27	P33	Port 3 pin 3	Input
28-32	P20-P24	Port 2 pin 0,1,2,3,4	In/Output
33	N/C	Not Connected (20 MHz)	Input
	/WAIT	WAIT (25 or 33 MHz)	Input
34-36	P25-P27	Port 2 pin 5,6,7	In/Output
37	P31	Port 3 pin 1	Input
38	P36	Port 3 pin 6	Output
39	V_{CC}	Power Supply	Input
40	XTAL2	Crystal, Osc. Clock	Output
41	XTAL1	Crystal, Osc. Clock	Input
42	P37	Port 3 pin 7	Output
43	P30	Port 3 pin 0	Input
44	SCLK	System Clock	Output

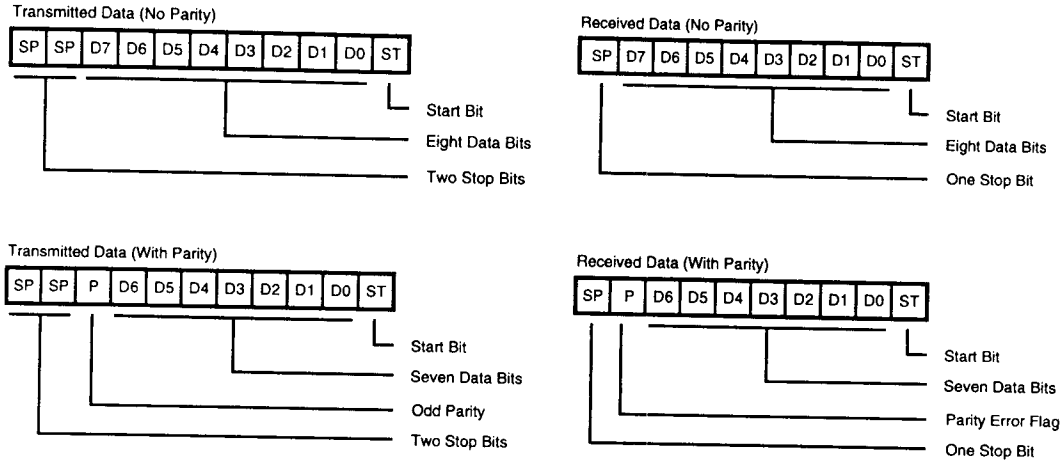


Figure 11. Serial Data Formats

ADDRESS SPACE

Program Memory. The Z86C93 can address up to 64 Kbytes of external program memory. Program execution begins at external location 000CH after a reset.

Data Memory. The Z96C93 can address up to 64 Kbytes of external data memory. External data memory is included with, or separated from, the external program memory space. /DM, an optional I/O function that can be programmed to appear on pin P34 is used to distinguish between data and program memory space (Figure 12). The state of the /DM signal is controlled by the type instruction being executed. An LDC opcode references PROGRAM (/DM inactive) memory, and an LDE instruction references DATA (/DM active Low) memory.

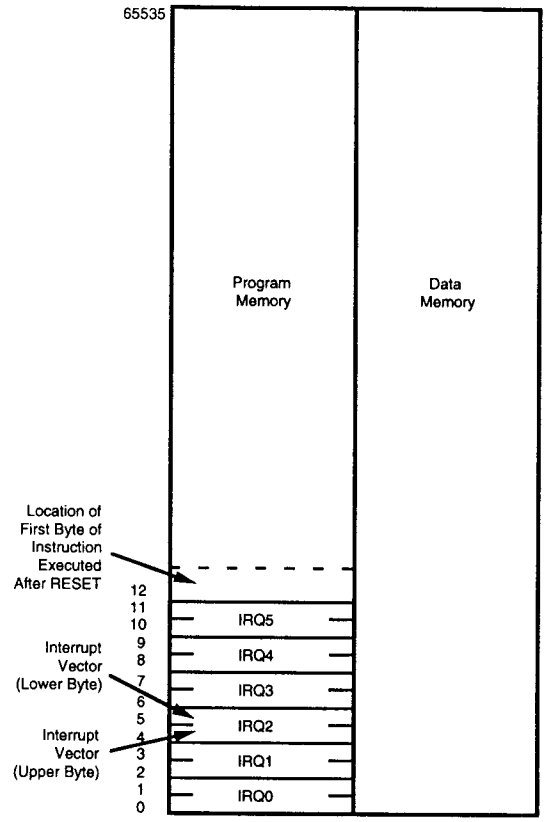


Figure 12. Program and Data Memory Configuration

Expanded Register File. The register file has been expanded to allow for additional system control registers, and for mapping of additional peripheral devices along with I/O ports into the register address area (Figure 13). The Z8 register address space R0 through R15 has now been implemented as 16 groups of 16 registers per group. These register groups are known as the ERF (Expanded Register File). Bits 7-4 of register RP select the working register group. Bits 3-0 of register RP select the expanded register group (Figure 14). The registers that are used in the multiply/divide unit reside in the Expanded Register File at Bank E and those for the additional timer control words reside in Bank D. The rest of the Expanded Register is not physically implemented and is open for future expansion.

Register File. The Register File consists of four I/O port registers, 236 general-purpose registers and 16 control and status registers. The instructions can access registers directly or indirectly via an 8-bit address field. The Z86C93 also allows short 4-bit register addressing using the Register Pointer (Figure 15). In the 4-bit mode, the Register File is divided into 16 working register groups, each occupying 16 continuous locations. The Register Pointer addresses the starting location of the active working-register group.

Note: Register Group E0-EF can only be accessed through working registers and indirect addressing modes.

Stack. The Z86C93 has a 16-bit Stack Pointer (R254-R255), used for external stack, that resides anywhere in the data memory. An 8-bit Stack Pointer (R255) is used for the internal stack that resides within the 236 general-purpose registers (R4-R239). The high byte of the Stack Pointer (SPH, Bits 8-15) can be used as a general-purpose register when using internal stack only.

FUNCTIONAL DESCRIPTION

This section breaks down the Z86C93 into its main functional parts.

Multiply/Divide Unit

The Multiply/Divide unit describes the basic features, implementation details of the interface between the Z8 and the multiply/divide unit.

Basic features:

- 16-bit by 16-bit multiply with 32-bit product
- 32-bit by 16-bit divide with 16-bit quotient and 16-bit remainder
- Unsigned integer data format
- Simple interface to Z8

Interface to Z8. The following is a brief description of the register mapping in the multiply/divide unit and its interface to the Z8 (Figure 16).

The multiply/divide unit is interfaced like a peripheral. The only addressing mode available with the peripheral interface is register addressing. In other words, all of the operands are in the respective registers before a multiplication/division can start.

Register mapping. The registers used in the multiply/divide unit are mapped onto the expanded register file in Bank E. The exact register locations used are shown below.

REGISTER	ADDRESS
MREG0	(E) 00
MREG1	(E) 01
MREG2	(E) 02
MREG3	(E) 03
MREG4	(E) 04
MREG5	(E) 05
MDCON	(E) 06
GPR	(E) 14
GPR	(E) 15

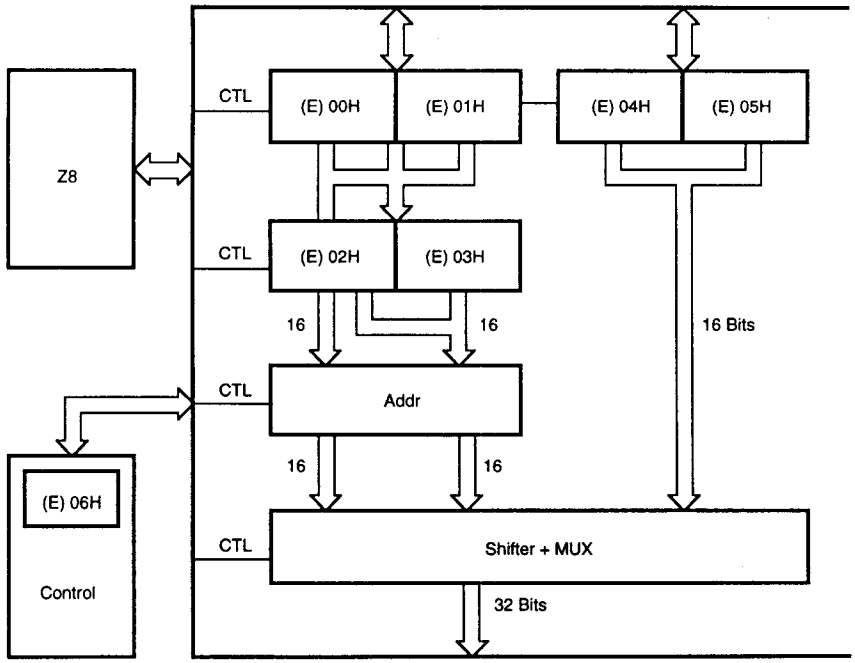


Figure 16. Multiply/Divide Unit Block Diagram

Power Down Modes

HALT. Turns off the internal CPU clock but not the XTAL oscillation. The counter/timers and the external interrupts IRQ0, IRQ1, IRQ2 and IRQ3 remain active. The devices are recovered by interrupts, either externally or internally generated. During HALT mode, /DS, /AS and R/W are HIGH. The outputs retain their preview value, and the inputs are floating.

STOP. This instruction turns off the internal clock and external crystal oscillation and reduces the standby current to 10 µA or less. The STOP mode is terminated by a /RESET, which causes the processor to restart the application program at address 000CH.

In order to enter STOP (or HALT) mode, it is necessary to first flush the instruction pipeline to avoid suspending execution in mid-instruction. To do this, the user executes a NOP (opcode=OFFH) immediately before the appropriate sleep instruction, i.e.:

```
FF  NOP   ; clear the pipeline
6F  STOP  ; enter STOP mode
          or
FF  NOP   ; clear the pipeline
7F  HALT  ; enter HALT mode
```

ABSOLUTE MAXIMUM RATINGS

Symbol	Description	Min	Max	Units
V_{CC}	Supply Voltage*	-0.3	+7.0	V
T_{STG}	Storage Temp	-65	+150	C
T_A	Oper Ambient Temp	†	†	C

* Voltages on all pins with respect to GND.
† See Ordering Information

Stress greater than those listed under Absolute Maximum Ratings may cause permanent damage to the device. This is a stress rating only; operation of the device at any condition above those indicated in the operational sections of these specifications is not implied. Exposure to absolute maximum rating conditions for an extended period may affect device reliability.

STANDARD TEST CONDITIONS

The characteristics listed below apply for standard test conditions as noted. All voltages are referenced to GND. Positive current flows into the referenced pin Test Load Diagram (Figure 23).

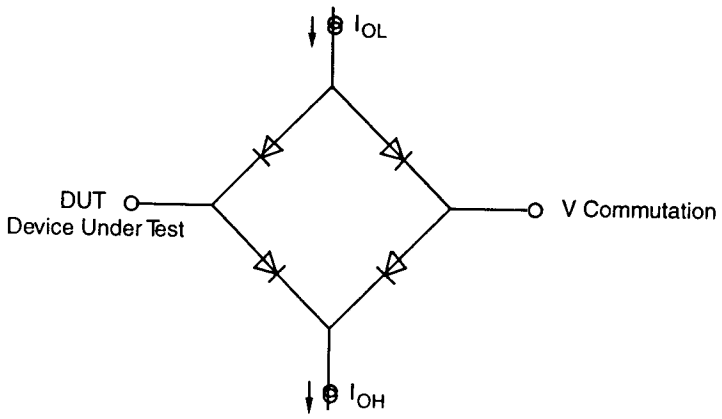


Figure 23. Test Load Diagram

DC ELECTRICAL CHARACTERISTICS

V_{CC} = 5.0V ± 10%

Sym	Parameter	T_A = 0°C to +70°C Min	Max	Typical at 25°C	Units	Conditions
	Max Input Voltage		7		V	I_{IN} 250 µA
V_{CH}	Clock Input High Voltage	3.8	V_{CC}		V	Driven by External Clock Generator
V_{CL}	Clock Input Low Voltage	-0.03	0.8		V	Driven by External Clock Generator
V_{IH}	Input High Voltage	2.0	V_{CC}		V	
V_{IL}	Input Low Voltage	-0.3	0.8		V	
V_{OH}	Output High Voltge	2.4			V	I_{OH}=-2.0 mA
V_{OH}	Output High Voltage	V_{CC} -100mV			V	I_{OH} = -100 µA
V_{OL}	Output Low Voltage		0.4		V	I_{OL} = +5 mA
V_{RH}	Reset Input High Voltage	3.8	V_{CC}		V	
V_{RI}	Reset Input Low Voltage	-0.03	0.8		V	
I_{IL}	Input Leakage	-2	2		µA	Test at 0V, V_{CC}
I_{OL}	Output Leakage	-2	2		µA	Test at 0V, V_{CC}
I_{IR}	Reset Input Current		-80		µA	V_{RL} = 0V
I_{CC}	Supply Current		55	35	mA	@ 33 MHz [1]
			40	25	mA	@ 25 MHz [1]
			30	20	mA	@ 20 MHz [1]
I_{CC1}	Standby Current (HALT Mode)		15	9	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 25 MHz [1]
			20	15		HALT Mode V_{IN} = 0V, V_{CC} @ 33 MHz [1]
			12	7	mA	HALT Mode V_{IN} = 0V, V_{CC} @ 20 MHz [1]
I_{CC2}	Standby Current (STOP Mode)		10	1	µA	STOP Mode V_{IN} = 0V, V_{CC} [1]
I_{AL}	Auto Latch Current	-16	16	5	µA	

Note:

[1] All inputs driven to 0V, or V_{cc} and outputs floating.

AC CHARACTERISTICS
Additional Timing Diagram

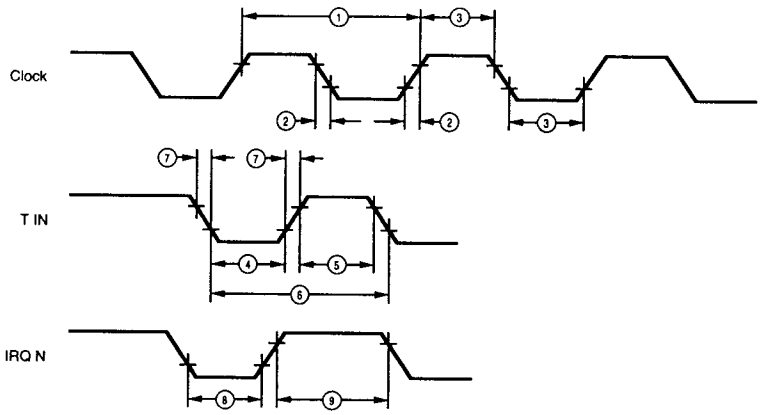


Figure 27. Additional Timing

AC CHARACTERISTICS
Additional Timing Table

No	Symbol	Parameter	T_A = 0°C to +70° C						Units	Notes
			33 MHz		24 MHz		20 MHz			
			Min	Max	Min	Max	Min	Max		
1	TpC	Input Clock Period	30	1000	42	1000	50	1000	ns	[1]
2	TrC,TfC	Clock Imput Rise & Fall Times		5		10		10	ns	[1]
3	TwC	Input Clock Width	10		11		15		ns	[1]
4	TwTinL	Timer Input Low Width	75		75		75		ns	[2]
5	TwTinH	Timer Input High Width	3TpC		3TpC		3TpC			[2]
6	TpTin	Timer Input Period	8TpC		8TpC		8TpC			[2]
7	TrTin,TfTin	Timer Input Rise & Fall Times	100		100		100		ns	[2]
8A	TwIL	Interrupt Request Input Low Times	70		70		70		ns	[2,4]
8B	TwIL	Interrupt Request Input Low Times	5TpC		5TpC		5TpC			[2,5]
9	TwIH	Interrupt Request Input High Times	3TpC		3TpC		3TpC			[2,3]

Notes:
[1] Clock timing references use 3.8V for a logic 1 and 0.8V for a logic 0.
[2] Timing references use 2.0V for a logic 1 and 0.8V for a logic 0.
[3] Interrupt references request via Port 3.
[4] Interrupt request via Port 3 (P31-P33)`.
[5] Interrupt request via Port 30.

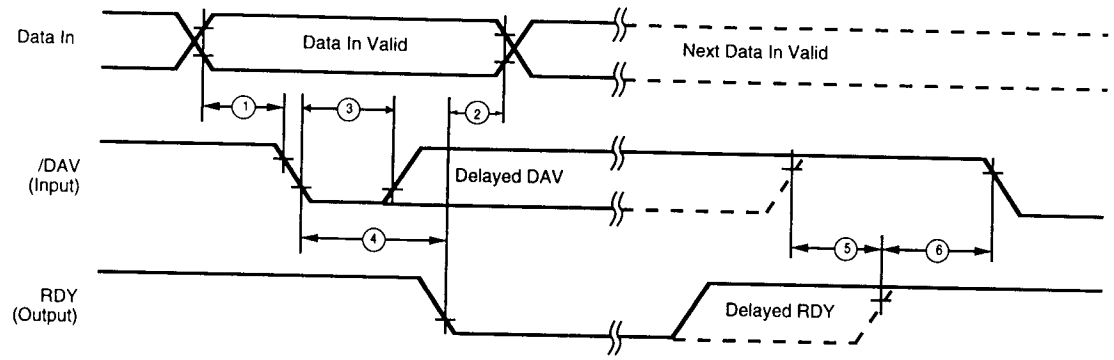


Figure 28. Input Handshake Timing

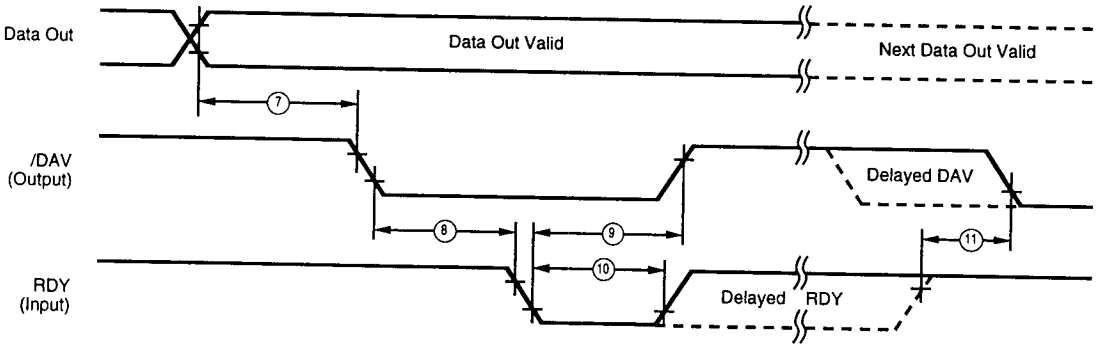


Figure 29. Output Handshake Timing

AC CHARACTERISTICS

Handshake Timing Table

No	Symbol	Parameter	T_A = 0°C to +70°C Min	Max	Units	Data Direction
1	TsDI(DAV)	Data In Setup Time to /DAV	0		ns	In
2	ThDI(DAV)	RDY to Data In Hold Time	0		ns	In
3	TwDAV	/DAV Width	40		ns	In
4	TdDAVIf(RDYf)	/DAV to RDY Delay		70	ns	In
5	TdDAVIr(RDYr)	DAV Rise to RDY Wait Time		40	ns	In
6	TdRDYOr(DAVIf)	RDY Rise to DAV Delay	0		ns	In
7	TdDO(DAV)	Data Out to DAV Delay		TpC	ns	Out
8	TdDAVOf(RDYIf)	/DAV to RDY Delay	0		ns	Out
9	TdRDYIf(DAVOr)	RDY to /DAV Rise Delay		70	ns	Out
10	TwRDY	RDY Width	40		ns	Out
11	TdRDYIr(DAVOf)	RDY Rise to DAV Wait Time		40	ns	Out

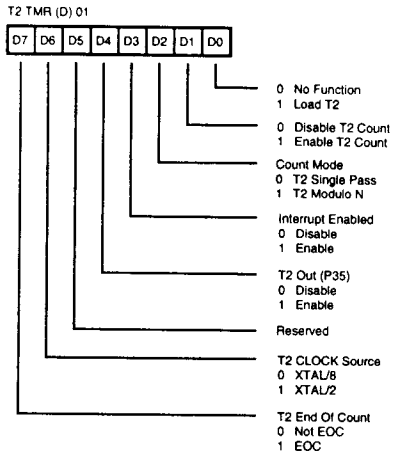


Figure 30. Timer 2 Mode Register (01H: Read/Write)

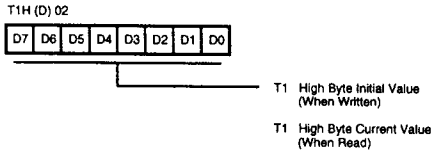


Figure 31. Counter Timer 1 Register High Byte (02H: Read/Write)

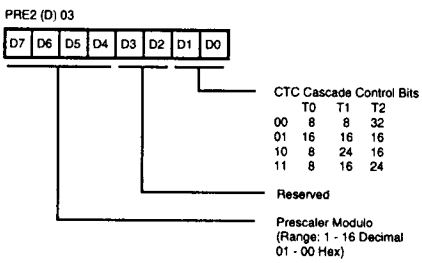


Figure 32. Prescaler 2 Register High Byte (03H: Write Only)

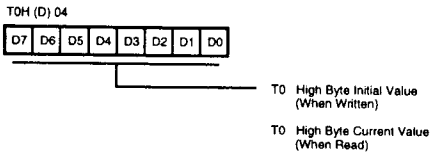


Figure 33. Counter Timer 0 Register High Byte (04H: Read/Write)

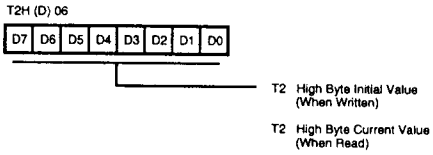


Figure 34. Counter Timer 2 Register High Byte (06H: Read/Write)

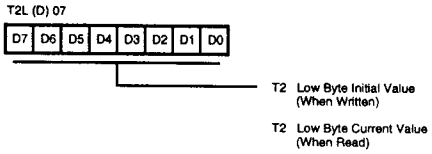


Figure 35. Counter Timer 2 Register Low Byte (07H: Read/Write)

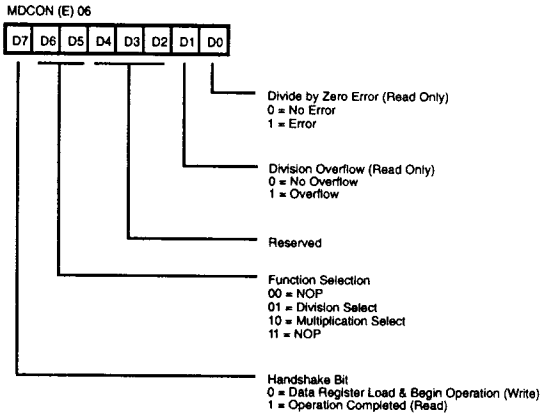


Figure 36. Multiply/Divide Control Register (MDCON)

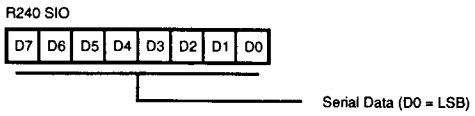


Figure 37. Serial I/O Register (F0H: Read/Write)

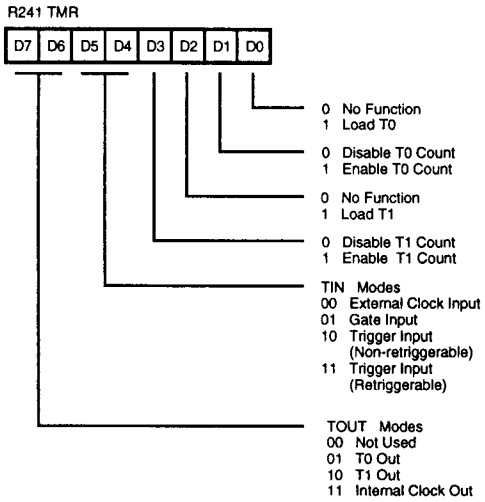


Figure 38. Timer Mode Register (F1H: Read/Write)

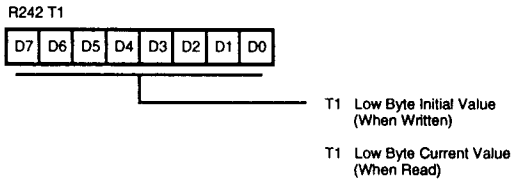


Figure 39. Counter/Timer 1 Register (F2H: Read/Write)

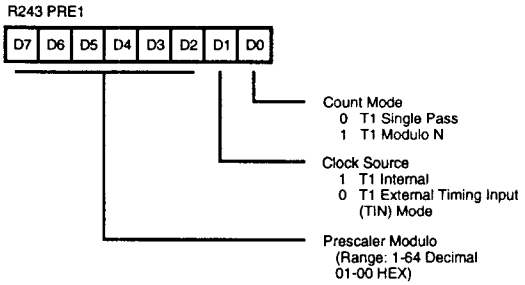


Figure 40. Prescaler 1 Register (F3H: Write Only)

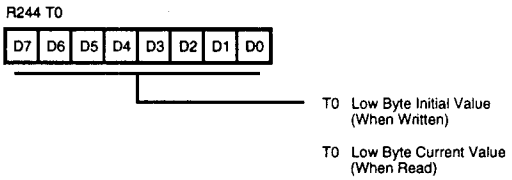


Figure 41. Counter/Timer 0 Register (F4H: Read/Write)

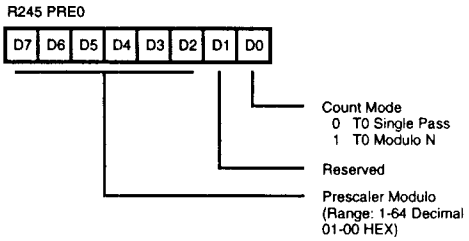


Figure 42. Prescaler 0 Register (F5H: Write Only)

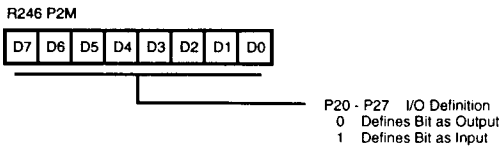


Figure 43. Port 2 Mode Register (F6H: Write Only)

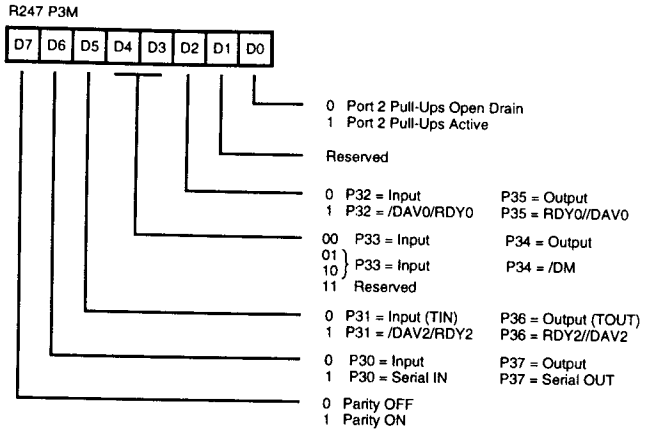


Figure 44. Port 3 Mode Register (F7H: Write Only)

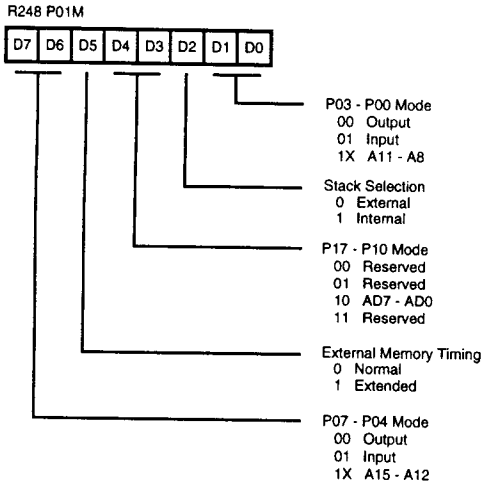


Figure 45. Ports 0 and 1 Mode Registers (F8H: Write Only)

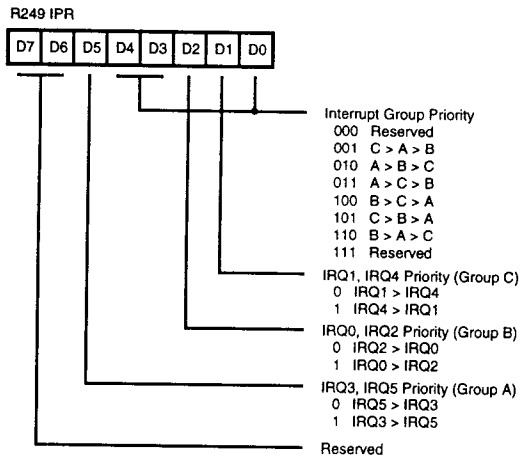


Figure 46. Interrupt Priority Register (F9H: Write Only)

INSTRUCTION SET NOTATION

Addressing Modes. The following notation is used to describe the addressing modes and instruction operations as shown in the instruction summary.

Symbol	Meaning
IRR	Indirect register pair or indirect working-register pair address
Irr	Indirect working-register pair only
X	Indexed address
DA	Direct address
RA	Relative address
IM	Immediate
R	Register or working-register address
r	Working-register address only
IR	Indirect-register or indirect working-register address
Ir	Indirect working-register address only
RR	Register pair or working register pair address

Symbols. The following symbols are used in describing the instruction set.

Symbol	Meaning
dst	Destination location or contents
src	Source location or contents
cc	Condition code
@	Indirect address prefix
SP	Stack Pointer
PC	Program Counter
FLAGS	Flag register (Control Register 252)
RP	Register Pointer (R253)
IMR	Interrupt mask register (R251)

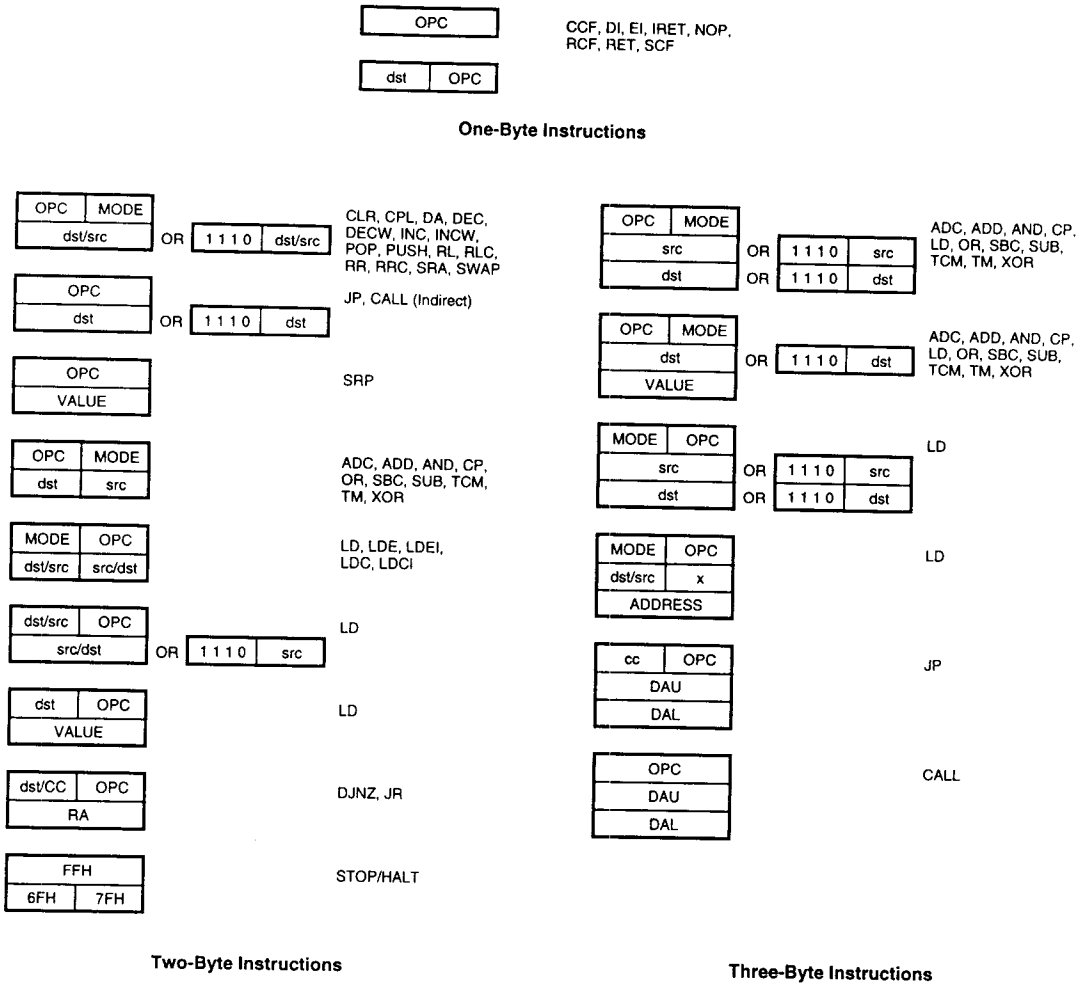
Flags. Control register (R252) contains the following six flags:

Symbol	Meaning
C	Carry flag
Z	Zero flag
S	Sign flag
V	Overflow flag
D	Decimal-adjust flag
H	Half-carry flag

Affected flags are indicated by:

0	Clear to zero
1	Set to one
*	Set to clear according to operation
-	Unaffected
x	Undefined

INSTRUCTION FORMATS



INSTRUCTION SUMMARY

Note: Assignment of a value is indicated by the symbol " ← ". For example:

dst ← dst + src

indicates that the source data is added to the destination data and the result is stored in the destination location. The notation "addr (n)" is used to refer to bit (n) of a given operand location. For example:

dst (7)

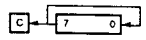
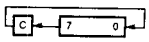
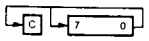
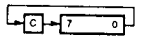
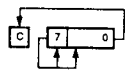
refers to bit 7 of the destination operand.

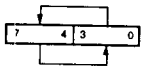
INSTRUCTION SUMMARY (Continued)

Instruction and Operation	Address Mode dst	Address Mode src	Opcode Byte (Hex)	Flags Affected C	Z	S	V	D	H
ADC dst, src dst←dst + src +C	†		1[ ]	*	*	*	*	0	*
ADD dst, src dst←dst + src	†		0[ ]	*	*	*	*	0	*
AND dst, src dst←dst AND src	†		5[ ]	-	*	*	0	-	-
CALL dst SP←SP - 2 @SP←PC, PC←dst	DA IRR		D6 D4	-	-	-	-	-	-
CCF C←NOT C			EF	*	-	-	-	-	-
CLR dst dst←0	R IR		B0 B1	-	-	-	-	-	-
COM dst dst←NOT dst	R IR		60 61	-	*	*	0	-	-
CP dst, src dst - src	†		A[ ]	*	*	*	*	-	-
DA dst dst←DA dst	R IR		40 41	*	*	*	X	-	-
DEC dst dst←dst - 1	R IR		00 01	-	*	*	*	-	-
DECW dst dst←dst - 1	RR IR		80 81	-	*	*	*	-	-
DI IMR(7)←0			8F	-	-	-	-	-	-
DJNZr, dst r←r - 1 if r ≠ 0 PC←PC + dst Range: +127, -128	RA		rA r = 0 - F	-	-	-	-	-	-
EI IMR(7)←1			9F	-	-	-	-	-	-
HALT			7F	-	-	-	-	-	-

Instruction and Operation	Address Mode dst	Address Mode src	Opcode Byte (Hex)	Flags Affected C	Z	S	V	D	H
INC dst dst←dst + 1	r		rE r = 0 - F	-	*	*	*	-	-
	R		20						
	IR		21						
INCW dst dst←dst + 1	RR IR		A0 A1	-	*	*	*	-	-
IRET FLAGS←@SP; SP←SP + 1 PC←@SP; SP←SP + 2; IMR(7)←1			BF	*	*	*	*	*	*
JP cc, dst if cc is true PC←dst	DA IRR		cD c = 0 - F 30	-	-	-	-	-	-
JR cc, dst if cc is true, PC←PC + dst Range: +127, -128	RA		cB c = 0 - F	-	-	-	-	-	-
LD dst, src dst←src	r	Im	rC	-	-	-	-	-	-
	r	R	r8						
	R	r	r9						
			r = 0 - F						
	r	X	C7						
	X	r	D7						
	r	Ir	E3						
	Ir	r	F3						
	R	R	E4						
	R	IR	E5						
	R	IM	E6						
	IR	IM	E7						
	IR	R	F5						
LDC dst, src	r	Irr	C2	-	-	-	-	-	-
LDCI dst, src dst←src r←r +1; rr←rr + 1	Ir	Irr	C3	-	-	-	-	-	-

INSTRUCTION SUMMARY (Continued)

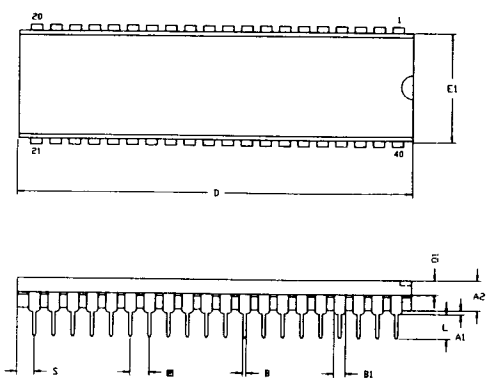
Instruction and Operation	Address Mode dst	Address Mode src	Opcode Byte (Hex)	Flags Affected C	Z	S	V	D	H
NOP			FF	-	-	-	-	-	-
OR dst, src dst←dst OR src	†		4[ ]	-	*	*	0	-	-
POP dst dst←@SP; SP←SP + 1	R IR		50 51	-	-	-	-	-	-
PUSH src SP←SP - 1; @SP←src		R IR	70 71	-	-	-	-	-	-
RCF C←0			CF	0	-	-	-	-	-
RET PC←@SP; SP←SP + 2			AF	-	-	-	-	-	-
RL dst 	R IR		90 91	*	*	*	*	-	-
RLC dst 	R IR		10 11	*	*	*	*	-	-
RR dst 	R IR		E0 E1	*	*	*	*	-	-
RRC dst 	R IR		C0 C1	*	*	*	*	-	-
SBC dst, src dst←dst←src←C	†		3[ ]	*	*	*	*	1	*
SCF C←1			DF	1	-	-	-	-	-
SRA dst 	R IR		D0 D1	*	*	*	0	-	-
SRP src RP←src		Im	31	-	-	-	-	-	-

Instruction and Operation	Address Mode dst	Address Mode src	Opcode Byte (Hex)	Flags Affected C	Z	S	V	D	H
STOP			6F	-	-	-	-	-	-
SUB dst, src dst←dst←src	†		2[ ]	*	*	*	*	1	*
SWAP dst 	R IR		F0 F1	X	*	*	X	-	-
TCM dst, src (NOT dst) AND src	†		6[ ]	-	*	*	0	-	-
TM dst, src dst AND src	†		7[ ]	-	*	*	0	-	-
XOR dst, src dst←dst XOR src	†		B[ ]	-	*	*	0	-	-

† These instructions have an identical set of addressing modes, which are encoded for brevity. The first opcode nibble is found in the instruction set table above. The second nibble is expressed symbolically by a '[ ]' in this table, and its value is found in the following table to the left of the applicable addressing mode pair.

For example, the opcode of an ADC instruction using the addressing modes r (destination) and Ir (source) is 13.

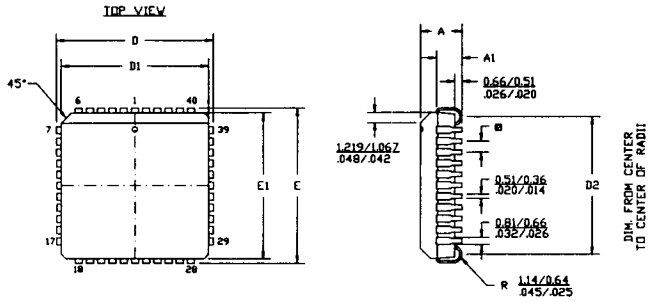
Address Mode dst	Address Mode src	Lower Opcode Nibble
r	r	[2]
r	Ir	[3]
R	R	[4]
R	IR	[5]
R	IM	[6]
IR	IM	[7]



SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A1	0.51	0.81	020	.032
A2	3.25	3.43	128	.135
B	0.38	0.53	015	021
B1	1.02	1.52	040	060
C	0.23	0.38	009	015
D	52.07	52.58	2.050	2.070
E	15.24	15.75	.600	.620
E1	13.59	14.22	.535	.560
eB	2.54 TYP		100 TYP	
eA	15.49	16.51	.610	.650
L	3.18	3.81	.125	150
D1	1.52	1.91	060	075
S	1.52	2.29	.060	.090

CONTROLLING DIMENSIONS : INCH

40-Pin DIP Package Diagram



NOTES:
1. CONTROLLING DIMENSIONS : INCH
2. LEADS ARE COPLANAR WITHIN .004 IN.
3. DIMENSION : MM
INCH

SYMBOL	MILLIMETER		INCH	
	MIN	MAX	MIN	MAX
A	4.27	4.57	.168	.180
A1	2.67	2.92	.105	.115
D/E	17.40	17.65	.685	.695
D1/E1	16.51	16.66	.650	.656
D2	15.24	16.00	.600	.630
eB	1.27 TYP		.050 TYP	

44-Pin PLCC Package Diagram

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